

Part Number: **B130LAW-7-F**  
Weight (mg): 10.671

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Die,Schottky	Doped silicon	Doped silicon *	7440-21-3	100.00%	3.832	0.409	1000000	38317
SOD-123 leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.070	2.995	576500	161826
		Ni	7440-02-0	41.00%			410000	115088
		Mn	7439-96-5	0.60%			6000	1684
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	281
		Co	7440-48-4	0.50%			5000	1404
		Si	7440-21-3	0.15%			1500	421
	Pure silver	Ag	7440-22-4	100.00%	0.852	0.091	1000000	8518
Bonding wire	2.0mil	Au	7440-57-5	100.00%	0.522	0.056	1000000	5219
Molding compound	KTMC-1050G	SiO2	60676-86-0	69.00%	63.577	6.784	690000	438678
		Epoxy Resin	29690-82-2	14.00%			140000	89007
		Phenol Resin	9003-35-4	7.00%			70000	44504
		Mg(OH)2	1309-42-8	8.00%			80000	50861
		C	1333-86-4	0.20%			2000	1272
		others	----	1.80%			18000	11444
Die attached epoxy	9005SP	Ag	7440-22-4	80.00%	1.147	0.122	800000	9177
		Bisphenol F	28064-14-4	15.00%			150000	1721
		Glycidyl neodeconate	26761-45-5	5.00%			50000	574
Tin solder	Pure Tin	Sn	7440-31-5	100.00%	2.001	0.213	1000000	20006
					100.00	10.671		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Antimony compounds	Organic tin compounds
Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including <b>DecaBDE</b>
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

This product or product family does not contain any chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHCs) under REACH. Please check the document at [http://www.diodes.com/files/products\\_lead\\_free/RoHS\\_Product\\_List.pdf](http://www.diodes.com/files/products_lead_free/RoHS_Product_List.pdf) for the current compliance status.